




Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-19
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement			
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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L99ASC03G	AAES*UI16BB1	A	ZY1A	2016-08-19
	Amount	UoM	Unit type	ST ECOPACK Grade
	140.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7x1	48	flat	
Comment	Package: TQFP 48 7x7x1.0 1.0 Exp Pad Down			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	true
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AAES*UI16BB1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	13.016	mg	supplier	die	Silicon (Si)	7440-21-3		12.557	mg	964736	89693
				supplier	metallization	Aluminium (Al)	7429-90-5		0.096	mg	7376	686
				supplier	metallization	Tungsten (W)	7440-33-7		0.077	mg	5916	550
				supplier	Passivation	Silicon Nitride	12033-89-5		0.020	mg	1537	143
				supplier	Passivation	Silicon Oxide	7631-86-9		0.165	mg	12677	1179
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.101	mg	7760	721
Leadframe	Copper & its alloys	51.053	mg	supplier	alloy	Copper (Cu)	7440-50-8		49.317	mg	965996	352264
				supplier	alloy	Iron (Fe)	7439-89-6		1.215	mg	23799	8679
				supplier	alloy	Phosphorous (P)	12185-10-3		0.015	mg	294	107
				supplier	alloy	Zinc (Zn)	7440-66-6		0.061	mg	1195	436
				supplier	metallization	Silver (Ag)	7440-22-4		0.445	mg	8716	3179
				supplier	glue	Silver (Ag)	7440-22-4		2.301	mg	789907	16436
Other organic materials	2.913	mg	supplier	glue	2,2'-(methylenebis(phenyleneoxymethylene))	39817-09-9		0.192	mg	65911	1371	
			supplier	glue	Dodeceny succinic anhydride	25377-73-5		0.192	mg	65911	1371	
			supplier	glue	2,6-Diglycidyl phenyl allyl ether	EC 417-470-1		0.076	mg	26090	543	
			supplier	glue	epoxy polymerised resin	Proprietary		0.076	mg	26090	543	
			supplier	glue	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8		0.076	mg	26090	543	
			supplier	wire	Gold (Au)	7440-57-5		0.829	mg	1000000	5921	
Bonding wires	Precious metals	0.829	mg	supplier	wire	Gold (Au)	7440-57-5		0.829	mg	1000000	5921
Encapsulation	Other inorganic materials	69.542	mg	supplier	mold compound	Epoxy Resin	25068-38-6		4.868	mg	70001	34771
				supplier	mold compound	Silica fused (SiO2) A	60676-86-0		50.069	mg	719982	357636
				supplier	mold compound	Silica fused (SiO2) B	7631-86-9		12.518	mg	180006	89414
				supplier	mold compound	Carbon Black	1333-86-4		0.348	mg	5004	2486
				supplier	mold compound	Phenol Resin	29690-82-2		1.739	mg	25006	12421
connections coating	Solder	2.647	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.647	mg	1000000	18907